LINGAYAS INSTITUTE OF MANAGEMENT AND TECHNOLOGY

Department of Electronics and Communication Engineering Course Handout for II Year B. Tech PROGRAM A.Y.2021 – 22, Ist Semester

Course Name

.

ELECTRONIC DEVICES & CIRCUITS

Course Code

PC01

L-T-P structure

3-1-2

Course Credits

.0

Course Instructor

U

Dr. D.S.P. PHANI KISHORE

Course Objective:

The main objectives of this course are:

To learn and understand the basic concepts of semiconductor physics.

Study the physical phenomena such as conduction, transport mechanism and electrical characteristics of different diodes.

 To learn and understand the application of diodes as rectifiers with their operation and characteristics with and without filters are discussed.

- Acquire knowledge about the principle of working and operation of Bipolar Junction Transistor and Field Effect Transistor and their characteristics.
- To learn and understand the purpose of transistor biasing and its significance.
- Small signal equivalent circuit analysis of BJT and FET transistor amplifiers and compare different configurations. on types of Sensors/ Transducers working principles, selection procedures, applications of sensing systems.

Course Rationale:

The course is taking by Second year students of ECE students to acquire the knowledge about the fundamental principles of electronic devices and circuits from the earlier silicon substrate version to latest insulated gate technology which will enabling the student to implement in their real-world applications. By learning the different electronic devices and their characteristics through theoretical and practical sessions, learners are well suitable to design the circuits and systems for the societal related problems. In this course the learners are aimed five outcomes which provide the knowledge about the fundamental principles of different electronic devices, circuits and their working and designing principles, selection criteria and applications.

Course Outcomes (CO):

CO No:	со	PO	BTL	
1	To Understand the formation of p-n junction and how it can be used as a PN junction as dlode in different modes of operation and special functions PN junctions	PO1, PO2	UNDERSTAND	
2	To Know the construction, working principle of rectifiers with and without filters with relevant expressions and necessary comparisons.	PO1, PO2	ANALYSE	
3	To Understand the construction, principle of operation of transistors, BIT and FET with their V-I characteristics in different configurations.	PO1, PO2, PSO1	UNDERSTAND	
4	To Know the need of transistor biasing, various biasing techniques for BJT and FET and stabilization concepts with necessary expressions.	. 52,1 52,1 551	ANALYSE	
S	To Perform the analysis of small signal low frequency transistor amplifier circuits using BJT	PO1, PO2	APPLY	

Lingaya s to sudur of Wart and A. L. Viveka Nagar, MADALAVAPIGUE a Wasa 2002 Nuzvir Road, Vijayawada Ruraf COURSE OUTCOME INDICATORS (COI):

CO No.	COI-1	COI-2
1	To Understand the formation of p-n junction, PN Diode, Modes	To understand about Special Semiconductor diodes
2	To Know the construction, working principle of rectifiers with and without filters	Using relevant expressions and necessary comparisons differentiation among the filter circuits
3	To Understand the construction, principle of operation of transistors, BJT and FET	The V-I characteristics and different configurations of BJT and FET
4	To Know the need of transistor biasing, biasing techniques for BJT and FET	Stabilization concepts with necessary expressions
5	To Perform the analysis of small signal low frequency transistor amplifier circuits using BJT	To Perform the analysis of small signal low frequency transistor amplifier circuits using FET

PROGRAM OUTCOMES (POs)

- a. Engineering Knowledge: Apply the knowledge of mathematics, science, engineering fundamentals, and an engineering specialization to the solution of complex engineering problems.
- b. Problem Analysis: Identify, formulate, review research literature, and analyze complex engineering problems reaching substantiated conclusions using first principles of mathematics, natural sciences, and engineering sciences.

PROGRAM SPECIFIC OUTCOMES (PSO)

At the end of the program, the student

PSO 1: should be able to understand the concepts of Electronics & Communication engineering and their applications in the field of semiconductor technology, consumer electronics, embedded system, communication/ networking and other relevant areas.

CO-PO Mapping Matrix

COs	PO1	POZ	PSO1
CO1	3	2	
CO2	3	2	
CO3	3	2	2
CO4	3	2	2
COS	3	2	
a. C. betantially	2: Moderatel	V	1: Poor

2: Moderately 3: Substantially

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SYLLABUS:

UNIT - I

Review of Semiconductor Physics:

Hall effect, continuity equation, law of junction, Fermi Dirac function, Fermi level in intrinsic and extrinsic Semiconductors
Junction Diode Characteristics: energy band diagram of PN junction Diode, Open circuited p-n junction, Biased p-n junction, p-n junction diode, current components in PN junction Diode, diode equation, V-I Characteristics, temperature dependence on VI characteristics, Diode resistance, Diode capacitance.

UNIT-II:

Special Semiconductor Devices: Zener Diode, Breakdown mechanisms, Zener diode applications,

LED, Varactor Diode, Photodiode, Tunnel Diode, UJT, PN-Diode, SCR. Construction, operation, and V-I characteristics.

Rectifiers and Filters: Basic Rectifier setup, half wave rectifier, full wave rectifier, Bridge rectifier, derivations of characteristics of rectifiers, rectifier circuits-operation, input and output waveforms, Filters, Inductor filter (Series inductor), Capacitor filter(Stunt inductor), π- Filter, comparison of various filter circuits in terms of ripple factors.

UNIT-III: Transistor Characteristics:

BJT: Junction transistor, transistor current components, transistor equation, transistor configurations, transistor as an amplifier, characteristics of transistor in Common Base, Common Emitter and Common Collector configurations, Ebers-Moll model of a transistor, punch through/reach through, Photo transistor, typical transistor junction voltage values.

FET: FET types, construction, operation, characteristics μ, gm, rd parameters, MOSFET-types, construction, operation, characteristics, comparison between JFET and MOSFET.

UNIT- IV: Transistor Biasing and Thermal Stabilization: Need for biasing, operating point, load line analysis, BJT biasing- methods, basic stability, fixed bias, collector to base bias, self-bias, Stabilization against variations in VBE, Ic, and β, Stability factors, (S,S',S"), Bias compensation, Thermal runaway, Thermal stability. FET Biasing-methods and stabilization.

UNIT-V: Small Signal Low Frequency Transistor Amplifier Models:

BJT: Two port network, Transistor hybrid model, determination of h-parameters, conversion Of h-parameters, generalized analysis of transistor amplifier model using h-parameters, Analysis of CB, CE and CC amplifiers using exact and approximate analysis, Comparison of Transistor amplifiers.

FET: Generalized analysis of small signal model, Analysis of CG, CS and CD amplifiers, comparison of FET amplifiers.

Textbooks:

- Electronic Devices and Circuits-J. Millman, C. Halkias, Tata Mc-Graw Hill, Second Edition, 2007
- Electronic Devices and Circuits-K. Lal Kishore, BS Publications, Fourth Edition, 2016.
- Electronics devices & circuit theory-Robert L. Boylestad and Loui Nashelsky, Pearson / Prentice Hall, tenth edition, 2009

References:

- Integrated Electronics-J. Millman, C. Halkias, Tata Mc-Graw Hill, Second Edition, 2009
- Electronic Devices and Integrated Circuits B.P. Singh, Rekha, Pearson publications
- Electronic Devices and Circuits-Salivahanan, Kumar, Vallava raj, Tata Mc-Graw Hill, 4thEdition.2008.

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COURSE DELIVERY PLAN:

S. No	со	соі	Topic (s)	Teaching-Learning Methods	Evaluation Components
1			Introduction to EDC course, Syllabus discussion COs and their significance demonstration, Assessment	Chalk & Talk	NA
2	1	1	Semiconductors and classification, Energy band theory	Chalk & Talk/ PPT	
3	1	1	Hall effect, continuity equation	Chalk & Talk/PPT	
4	1	1	law of junction, Fermi Dirac function, Fermi level in intrinsic and extrinsic Semiconductors	Chalk & Talk/PPT	
5	1	1	Junction Diode Characteristics	Chalk & Talk/PPT	1
6	1	1	Energy band diagram of PN junction Diode	Chalk & Talk/PPT	
7	1	1	Open circuited p-n Junction, Blased p-n Junction	Chalk & Talk/PPT	
8	1	1	p-n junction diode, characteristics	Chalk & Talk/PPT	
9	1	1	current components In PN junction Diode	Chalk & Talk/PPT	
10	1	1	Diode equation, temperature dependence	Chalk & Talk/PPT	
11	1	1	Diode resistance and capacitance	Chalk & Talk/PPT	Quiz, Home Assignments,
12	1	2	Zener Diode, Breakdown mechanisms, Zener diode applications	Chalk & Talk/PPT	CBT, OBT, Poli
13	1	2	LED, Varactor Diode, Photodiode, Tunnel Diode	Chalk & Talk/PPT	questions, MID-
14	1	2	UJT, PN-Diode, SCR, and its V-I characteristics	Chalk & Talk/PPT	1, SEM End
15	2	1	Basic Rectifier setup, half wave rectifier	Chalk & Talk/PPT	Exam
16	2	1	Full wave rectifier, Bridge rectifier	Chalk & Talk/PPT	
	_		derivations of characteristics of rectifiers, rectifier circuits-	Chalk & Talk/PPT	
17	2	1	operation, input, and output waveforms	Chair & Tallyrri	
18	2	1	derivations of characteristics of rectifiers, rectifier circuits- operation, input, and output waveforms	Chalk & Talk/PPT	
19	2	2	Filters, Inductor filter (Series inductor)	Chalk & Talk/PPT	
20	2	2	Capacitor filter (Stunt Inductor), π - Filter, comparison of various filter circuits in terms of ripple factors.	Chalk & Talk/PPT	
21	3	1	BJT: Junction transistor, transistor current components,	Chalk & Talk/PPT	
22	3	1	transistor equation, transistor configurations	Chalk & Talk/PPT	
23	3	1	transistor as an amplifier	Chalk & Talk/PPT	
43				-1 11	
24	3	1	FET: and its current components,	Chalk & Talk/PPT	
	3	1		Chalk & Talk/PPT Chalk & Talk/PPT	
24	-		Current equation, configurations FET as an amplifier		
24 25	3	1	Current equation, configurations FET as an amplifier characteristics of transistor in Common Base, Common Emitter and Common Collector configurations	Chalk & Talk/PPT	
24 25 26	3	1	Current equation, configurations FET as an amplifier characteristics of transistor in Common Base, Common Emitter and Common Collector configurations characteristics of transistor in Common Base, Common Emitter and Common Collector configurations	Chalk & Talk/PPT Chalk & Talk/PPT	
24 25 26 27	3 3	1 1 2	Current equation, configurations FET as an amplifier characteristics of transistor in Common Base, Common Emitter and Common Collector configurations characteristics of transistor in Common Base, Common Emitter and Common Collector configurations Ebers-Moll model of a transistor, punch through/reach through	Chalk & Talk/PPT Chalk & Talk/PPT Chalk & Talk/PPT	
24 25 26 27 28	3 3 3	1 2 2	Current equation, configurations FET as an amplifier characteristics of transistor in Common Base, Common Emitter and Common Collector configurations characteristics of transistor in Common Base, Common Emitter and Common Collector configurations Ebers-Moll model of a transistor, punch through/reach through Photo transistor, typical transistor junction voltage values	Chalk & Talk/PPT Chalk & Talk/PPT Chalk & Talk/PPT Chalk & Talk/PPT	
24 25 26 27 28 29	3 3 3 3 3 3	1 1 2 2 2 2 2 2	Current equation, configurations FET as an amplifier characteristics of transistor in Common Base, Common Emitter and Common Collector configurations characteristics of transistor in Common Base, Common Emitter and Common Collector configurations Ebers-Moll model of a transistor, punch through/reach through Photo transistor, typical transistor junction voltage values characteristics µ, gm, rd parameters,	Chalk & Talk/PPT	
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24 25 26 27 28 29 30 31	3 3 3 3 3 3 3 3	1 1 2 2 2 2 2 2 2 2 2 2	Current equation, configurations FET as an amplifier characteristics of transistor in Common Base, Common Emitter and Common Collector configurations characteristics of transistor in Common Base, Common Emitter and Common Collector configurations Ebers-Moll model of a transistor, punch through/reach through Photo transistor, typical transistor junction voltage values characteristics µ, gm, rd parameters, MOSFET-types, construction, operation characteristics, comparison between JEET and MOSFET.	Chalk & Talk/PPT	Quiz, Home
24 25 26 27 28 29 30 31 32 33 34	3 3 3 3 3 3 3 3 4	1 1 2 2 2 2 2 2 2 2 2 2	Current equation, configurations FET as an amplifier characteristics of transistor in Common Base, Common Emitter and Common Collector configurations characteristics of transistor in Common Base, Common Emitter and Common Collector configurations Ebers-Moll model of a transistor, punch through/reach through Photo transistor, typical transistor junction voltage values characteristics µ, gm, rd parameters, MOSFET-types, construction, operation characteristics, comparison between JEET and MOSFET. Need for biasing, operating point	Chalk & Talk/PPT	Assignments,
24 25 26 27 28 29 30 31 32 33	3 3 3 3 3 3 3 3	1 1 2 2 2 2 2 2 2 2 2 2	Current equation, configurations FET as an amplifier characteristics of transistor in Common Base, Common Emitter and Common Collector configurations characteristics of transistor in Common Base, Common Emitter and Common Collector configurations Ebers-Moll model of a transistor, punch through/reach through Photo transistor, typical transistor junction voltage values characteristics µ, gm, rd parameters, MOSFET-types, construction, operation characteristics, comparison between JEET and MOSFET.	Chalk & Talk/PPT	1

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38	4	2	basic stability	Chalk & Talk/PPT	Exam
39	4	2	Stabilization against variations in VBE, Ic, and β, Stability factors	SI . II O T . II (DDT	
40	4	2	Stabilization against variations in VBE, IC, and B, Stability factors	Chalk & Talk/PPT	
41	4	2	(S, S', S"), Bias compensation, Thermal runaway, Thermal stability	Chalk & Talk/PPT	
42	4	2	FET Biasing-methods and stabilization.	Chalk & Talk/PPT	
43	4	2	FET methods of stabilization.	Chalk & Talk/PPT	
44	5	1	BJT: Two port network, Transistor hybrid model	Chalk & Talk/PPT	
45	5	1	determination of h-parameters	Chalk & Talk/PPT	
46	5	1	Conversion Of h-parameters	Chalk & Talk/PPT	
47	5	1	generalized analysis of transistor amplifier model using h-parameters	Chalk & Talk/PPT	
48	5	1	Analysis of CB, CE and CC ampliflers using exact and approximate	Challe 9 Talle/00T	
49	5	1	analysis	Chalk & Talk/PPT	
50	5	2	FET: Generalized analysis of small signal model	Chalk & Talk/PPT	
51	5	2	Analysis of CC CC and CD annullificate	Chalk & Talk/PPT	
52	5	2	Analysis of CG, CS and CD amplifiers	Chair & Talk/PPT	
53	5	2	Comparison of FET amplifiers	Chalk & Talk/PPT	

S. No	Date planned	lopic (S)		Teaching- Learning Methods	Remarks
1	05.09.2021	Introduction to EDC course, Syllabus discussion COs and their significance demonstration, Assessment		Chalk & Talk	
2	06.09.2021 07.09.2021	Semiconductors and classification, Energy band theory		Chalk & Talk/ PPT	
3	08.09.2021	Hall effect, continuity equation		Chalk & Talk/PPT	
4	09.09.2021 law of junction, Ferml Dirac function, Fermi level in 12.09.2021 intrinsic and extrinsic Semiconductors			Chalk & Talk/PPT	
5	13.09.2021	Junction Diode Characteristics		Chalk & Talk/PPT	
6	14.09.2021	Energy band diagram of PN junction Diode		Chalk & Talk/PPT	
7	16.09.2021	Open circuited p-n junction, Biased p-n junction		Chalk & Talk/PPT	
	19.09.2021	p-n junction diode, characteristics		Chalk & Talk/PPT	
9	20.09.2021 21.09.2021 current components in PN junction Diode		Chalk & Talk/PPT		
10		Diode equation, temperature dependence		Chalk & Talk/PPT	
10	22.09.2021	Diode resistance and capacitance		Chalk & Talk/PPT	
11_	26.09.2021	Zener Diode, characteristics		Chalk & Talk/PPT	
12		Breakdown mechanisms		Chalk & Talk/PPT	
13	27.09.2021	Zener diode applications: voltage regulator		Chalk & Talk/PPT	
15	29.09.2021	LED, Varactor Diode		Chalk & Talk/PPT	
16	30.09.2021	Photodiode, Tunnel Diode		Chalk & Talk/PPT	
17	07.10.2021	UIT, PN-Diode		Chalk & Talk/PPT	
18	10.10.2021	SCR, and its V-I characteristics		Chalk & Talk/PPT	
19	11.10.2021	Basic Rectifier setup, Half wave rectifier			
20	12.10.2021	derivations of characteristics of half-wave rectifiers, rectifier circuits-operation, input, and output waveforms		St. W. O. T. W. (207	
21	13.10.2021	Sull wave rectifier, Bridge rectifier		Chalk & Talk/PPT	
21	14.10.2021	derivations of characteristics of rectifiers, rectifier circuits-operation, input, and output waveforms		Chalk & Talk/PPT	
23	17.10.2021	Filters Inductor filter (Series inductor)		Chalk & Talk/PPT	
24	18.10.2021	Capacitor filter (Stunt inductor), π- Filter, comparison of		Chalk & Talk/PPT	-
35	19.10.2021	BIT: Junction transistor, transistor current components,		Chalk & Talk/PPT	-
25		transistor equation, transistor configurations		Chalk & Talk/PPT	-
26	20.10.2021	transistor as an amplifier		Chalk & Talk/PPT	
27	21.10.2021	WIID	1	Challe 9 Tall /DDT	Т
28	31 10.2021	FET: and its current components,		Chalk & Talk/PPT Chalk & Talk/PPT	1
29	01.11.2021	Current equation, configurations	-	Chalk & Talk/PPT	
30	02 11.2021	FET as an amplifier		Chalk & Talk/PPT	
31	03 11 2021 04 11 2021			Chalk & Talk/PPT	

OS.11.2021 Emitter and Common Collector configurations O9.11.2021 Ebers-Moll model of a transistor, punch through/reach Chalk & Talk/PPT
10.11.2021 through Photo transistor, typical transistor junction voltage values 11.11.2021 characteristics μ, gm, rd parameters, 15.11.2021 MOSFET-types, construction, operation 16.11.2021 characteristics, comparison between JFET and MOSFET. Chalk & Talk/PPT Chalk & Talk/PPT Chalk & Talk/PPT Red for biasing, operating point Chalk & Talk/PPT Date for biasing, operating point Chalk & Talk/PPT Chalk & Talk/PPT Chalk & Talk/PPT Date for biasing-methods Chalk & Talk/PPT Stabilization against variations in VBE, Ic, and β, Chalk & Talk/PPT
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36 15.11.2021 MOSFET-types, construction, operation 37 16.11.2021 characteristics, comparison between JFET and MOSFET. 38 17.11.2021 Need for biasing, operating point 39 18.11.2021 load line analysis 40 21.11.2021 BJT biasing-methods 41 22.11.2021 BJT biasing-methods 42 23.11.2021 basic stability 43 24.11.2021 Stabilization against variations in VBE, Ic, and β, Chalk & Talk/PPT 44 25.11.2021 Stability factors 45 Chalk & Talk/PPT 46 Chalk & Talk/PPT 47 Chalk & Talk/PPT 48 Chalk & Talk/PPT 49 Chalk & Talk/PPT 40 Chalk & Talk/PPT 41 Chalk & Talk/PPT 42 Chalk & Talk/PPT 43 Chalk & Talk/PPT 44 25.11.2021 Stability factors
37 16.11.2021 characteristics, comparison between JFET and MOSFET. Chalk & Talk/PPT 38 17.11.2021 Need for biasing, operating point Chalk & Talk/PPT 39 18.11.2021 load line analysis Chalk & Talk/PPT 40 21.11.2021 BJT biasing- methods Chalk & Talk/PPT 41 22.11.2021 BJT biasing- methods Chalk & Talk/PPT 42 23.11.2021 basic stability Chalk & Talk/PPT 43 24.11.2021 Stabilization against variations in VBE, Ic, and β, Chalk & Talk/PPT 44 25.11.2021 Stability factors
38 17.11.2021 Need for biasing, operating point Chalk & Talk/PPT 39 18.11.2021 load line analysis Chalk & Talk/PPT 40 21.11.2021 BJT biasing-methods Chalk & Talk/PPT 41 22.11.2021 BJT biasing-methods Chalk & Talk/PPT 42 23.11.2021 basic stability Chalk & Talk/PPT 43 24.11.2021 Stabilization against variations in VBE, Ic, and β, Chalk & Talk/PPT 44 25.11.2021 Stability factors Chalk & Talk/PPT 45 Chalk & Talk/PPT 46 Chalk & Talk/PPT 47 Chalk & Talk/PPT 48 Chalk & Talk/PPT 49 Chalk & Talk/PPT 49 Chalk & Talk/PPT 40 Chalk & Talk/PPT 41 Chalk & Talk/PPT 42 Chalk & Talk/PPT 43 Chalk & Talk/PPT 44 Chalk & Talk/PPT 45 Chalk & Talk/PPT 46 Chalk & Talk/PPT 47 Chalk & Talk/PPT 48 Chalk & Talk/PPT 49 Chalk & Talk/PPT 40 Chalk & Talk/PPT 41 Chalk & Talk/PPT 42 Chalk & Talk/PPT 43 Chalk & Talk/PPT 44 Chalk & Talk/PPT 45 Chalk & Talk/PPT 46 Chalk & Talk/PPT 47 Chalk & Talk/PPT 48 Chalk & Talk/PPT 49 Chalk & Talk/PPT 40 Chalk & Talk/PPT 41 Chalk & Talk/PPT 42 Chalk & Talk/PPT 43 Chalk & Talk/PPT 44 Chalk & Talk/PPT 45 Chalk & Talk/PPT 46 Chalk & Talk/PPT 47 Chalk & Talk/PPT 48 Chalk & Talk/PPT 49 Chalk & Talk/PPT 40 Chalk & Talk/PPT 40 Chalk & Talk/PPT 41 Chalk & Talk/PPT 42 Chalk & Talk/PPT 43 Chalk & Talk/PPT 44 Chalk & Talk/PPT 45 Chalk & Talk/PPT 46 Chalk & Talk/PPT 47 Chalk & Talk/PPT 48 Chalk & Talk/PPT 49 Chalk & Talk/PPT 40 Chalk & Talk/PPT 40 Chalk & Talk/PPT 41 Chalk & Talk/PPT 42 Chalk & Talk/PPT 43 Chalk & Talk/PPT 44 Chalk & Talk/PPT 45 Chalk & Talk/PPT 46 Chalk & Talk/PPT 47 Chalk & Talk/PPT 48 Chalk & Talk/PPT 49 Chalk & Talk/PPT 40 Chalk & Talk/PPT 40 Chalk & Talk/PPT 41 Chalk & Talk
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44 25.11.2021 Stability factors Chark & Talk/PPT
40 44 500 50
45 28.11.2021 (S, S', S"), Bias compensation, Thermal runaway, Thermal stability Chalk & Talk/PPT
46 29.11.2021 FET Biasing-methods and stabilization. Chalk & Talk/PPT
47 30.11.2021 FET methods of stabilization. Chalk & Talk/PPT
48 01.12.2021 BJT: Two port network, Transistor hybrid model Chalk & Talk/PPT
49 02.12.2021 determination of h-parameters Chalk & Talk/PPT
50 05.12.2021 Conversion Of h-parameters Chalk & Talk/PPT
51 06.12.2021 generalized analysis of transistor amplifier model using h-parameters Chalk & Talk/PPT
52 07.12.2021 Analysis of CB, CE and CC amplifiers using exact and Chalk & Talk/PPT
53 U8.12.2021 approximate analysis
54 09.12.2021 FET: Generalized analysis of small signal model Chalk & Talk/PPT
55 12.12.2021 Analysis of CG, CS and CD amplifiers Chalk & Talk/PPT
56 13.12.2021 Analysis of Co, Co and Co amplifiers
57 14.12.2021 Comparison of FET amplifiers Chalk & Talk/PPT
58 15.12.2021 Revision of CO 1, 2 Chalk & Talk/PPT
59 16.12.2021 Revision of CO 3, 4, 5 Chalk & Talk/PPT
60 19.12.2021 Model Papers Chalk & Talk/PPT
MID-II

EVALUATION PLAN:

		omponent Assessment type		Date	со				Evaluation	
S. No	Component			Date	1	2	3	4	done by	
		MID-1	Descriptive	24.10.2021 to 29.10.2021	х	Х				
			MID-2	19.11.2021 to 24 11.2021			х	х	Dr DSPPK	
		Internal Quiz-2 ty	Objective	24.10.2021 to 29 10.2021	x	x				
			Quiz-2	type	19.11.2021 to 24.11.2021			х	х	ONLINE
1	Theory		A-1	Home		X				
	1	A	A-2	Assignment			X	-	-	1
			A-3	s for each			-	X		Dr DSPPK
			A-4	со					X	1
		External Univ. I Assessment Exam	Descriptive type	02 01 2023 to 14 01 2023	x	×	x	x	University	

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Self-Learning:

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Course Team members, Chamber Consultation Hours and Chamber Venue details:

Course re-	and inclinating			Chamber	and Courte	
S. No.	Name of Faculty	Chamber Consultation Day(s)		Consultation Room No:	Signature of Course faculty	
1	Dr DSP PHANI KISHORE	All Weekdays	After 3pm	215		

Time Table

				11.10	12,30 1.10	2.10	3.00
Day	8.30	9.20	10.20	11.10	30		
MON		SS			14016	EDAVAB	
TUE		7007000	-				
WED	SS	10:	1706	1		9	S
THU	man but the factor was a second	- Inches	SS				
FRI		1301	33			SS	
SAT	SS						

Signature of COURSE INSTRUCTOR:

Recommended by HEAD OF DEPARTMENT:

Approved By: Incharge ACADEMICS

(Sign with Office Seal)

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Lingayas Institute of Management and Technology

(Approved by A I C T E - New Delhi & Affiliated to J N T University Kakinada)

Madalavarigudem, Vijayawada.

INSTRUCTION DIVISION

III YEAR FIRST SEMESTER 2021-2022

(BIOMETRIC SYSTEM OF ATTENDENCE IS MANDATORY AS PER NOMS OF GOVT. OF AP AND INTUK)

Course Handout

In addition to Part I (General Handout for all courses appended to the Time Table) this portion further specific details regarding the course.

LTPC

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Course Code

R1931042

Course Title

MICROPROCESSOR AND MICROCONTROLLERS

Instructor-in-charge

Prof. T. HEMALATHA

Scope and objective of the course: The objective of this course is:

Course objectives: The main objectives of this course are

- To acquire knowledge on microprocessors and microcontrollers.
- To select processors based on requirements.
- To acquire the knowledge on interfacing various peripherals, configure and develop programs to interface peripherals/sensors.
- To develop programs efficiently on ARM Cortex processors and debug

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SYLLABUS

UNIT-I

Introduction: Basic Microprocessor architecture, Harvard and Von Neumann architectures with examples, Microprocessor Unit versus Microcontroller Unit, CISC and RISC architectures.

8086 Architecture: Main features, pin diagram/description, 8086 microprocessor family, internal architecture, bus interfacing unit, execution unit, interrupts and interrupt response, 8086 system timing, minimum mode and maximum mode configuration.

II-TINU

8086 Programming: Program development steps, instructions, addressing modes, assembler directives, writing simple programs with an assembler, assembly language program development tools.

UNIT-III

8086 Interfacing: Semiconductor memories interfacing (RAM, ROM), Intel 8255 programmable peripheral interface, Interfacing switches and LEDS, Interfacing seven segment displays, software and hardware interrupt applications, Intel 8251 USART architecture and interfacing, Intel 8237a DMA controller, stepper motor, A/D and D/A converters, Need for 8259 programmable interruptcontrollers.

UNIT-IV

Intel 8051 MICROCONTROLLER

Architecture, Hardware concepts, Input / output ports and circuits, external memory, counters / timers, serial data input/output, interrupts.

Assembly language programming: Instructions, addressing modes, simple programs. Interfacing to 8051: A/D and D/A Convertors, Stepper motor interface, keyboard, LCD Interfacing, Traffic light control.

UNIT-V

ARM Architectures and Processors: ARM Architecture, ARM Processors Families, ARM Cortex-M Series Family, ARM Cortex-M3 Processor Functional Description, functions and interfaces.

Programmers Model – Modes of operation and execution, Instruction set summary, System address map, write buffer, bit-banding, processor core register summary, exceptions.

ARM Cortext-M3 programming – Software delay, Programming techniques, Loops, Stack and Stack pointer, subroutines and parameter passing, parallel 1/0, Nested Vectored Interrupt Controller – functional description and NVIC programmers' model.

Study Material:

TEXT BOOKS:

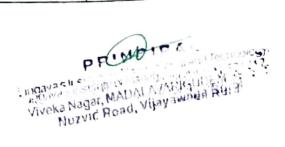
- Microprocessors and Interfacing Programming and Hardware by Douglas V Hall, SSSP Rao, Tata McGraw Hill Education Private Limited, 3rd Edition, 1994.
- The 8051 Microcontrollers and Embedded systems Using Assembly and C, Muhammad Ali Mazidi and Janice Gillespie Mazidi and Rollin D. McKinlay; Pearson 2-Edition, 2011.
- 3. The Definitive Guide to ARM Cortex-M3 and Cortex-M4 Processors by JosephYou.

REFERENCE BOOKS:

- 1. Embedded Systems Fundamentals with Arm Cortex-M based Microcontrollers: A Practical Approach in English, by Dr. Alexander G. Dean, Published by Arm Education Media, 2017.
- 2. Cortex -M3 Technical Reference Manual.

UNIT/MODULE	TOPIC	Duration	Textbook/Reference book/Source
	UNIT-1		
1.0	Basic Microprocessor architecture	50/60 mins	T1, R1
1.1	Microprocessor Unit versus Microcontroller Unit	50/60 mins	T1, R1
1.2	Harvard and Von Neumann architectures with examples, CISC and RISC architectures	50/60 mins	T1, R1
1.3	8086 Architecture: Main features	50/60 mins	T1, R1
1.4	Pin diagram/description	50/60 mins	T1, R1
1.5	Pin diagram/description	50/60 mins	T1, R1
1.6	8086 microprocessor family	50/60 mins	T1, R1
1.7	8086 Internal Architecture - BIU	50/60 mins	T1, R1
1.8	8086 Internal Architecture – EU	50/60 mins	T1, R1
1.9	Interrupts and interrupt responses	50/60 min:	
1.10	8086 system timing	50/60 min	
1.11	Minimum mode configuration	50/60 min	s T1, R1
1.12	Maximum mode configuration	50/60 min	

	UNIT-2			
2.0	8086 Programming: Program development steps	50/60 mins	T2, R1	
2.1	Instructions	50/60 mins	T2, R1	
2.2	Instructions	50/60 mins	T2, R1	
2.3	Addressing modes	50/60 mins	T2, R1	
2.4	Assembler directives	50/60 mins	T2, R1	
2.5	Writing simple programs with an assembler	50/60 mins	T2, R1	
2.6	Writing simple programs with an assembler	50/60 mins	T2, R1	
2.7	Assembly language program development tools	50/60 mins	T2, R1	
2.8	Assembly language program development tools	50/60 mins	T2, R1	
	UNIT-3			
3.0	8086 Interfacing: Semiconductor memories interfacing (RAM, ROM)	50/60 mins	Т1	
3.1	Intel 8255 programmable peripheral interface	50/60 mins	T1	
3.2	Interfacing switches and LEDS	50/60 mins		
3.3	Interfacing seven segment displays	50/60 mins	T1	
3.4	software and hardware interrupt applications	50/60 mins	Т1	
3.5	software and hardware interrupt applications	50/60 mins	T1	
3.6	Intel 8251 USART architecture	50/60 mins	T1	
3.7	Intel 8251 USART interfacing	50/60 mins	T1	
3.8	Intel 8237a DMA controller	50/60 mins	T1	
3.9	Stepper motor	50/60 mins	T1	
3.10	A/D and D/A converters	50/60 mins	T1	
3.11	Need for 8259 programmable interrupt controllers	50/60 mins	T1	
	UNIT-4			
4.0	Intel 8051 MICROCONTROLLER Architecture	50/60 mins	T1, T2, R1	
	Hardware concepts	50/60 mins	T1, T2, R1	
4.1	Input/output ports and circuits	50/60 mins	T1, T2, R1	
4.2	Input/output ports and circuits	50/60 mins	T1, T2, R1	
4.3	External memory	50/60 mins	T1, T2, R1	



4.5	Counters/timers,	50/60 mins	T1, T2, R1				
4.6	Serial data input/output	50/60 mins	T1, T2, R1				
4.7	Interrupts	50/60 mins	T1, T2, R1				
4.8	Assembly language programming: Instructions	50/60 mins	T1, T2, R1				
4.9	Addressing modes	50/60 mins	T1, T2, R1				
4.10	Simple programs	50/60 mins	T1, T2, R1				
4.11	Simple programs	50/60 mins	T1, T2, R1				
4.12	Interfacing to 8051: A/D and D/A converters	50/60 mins	T1, T2, R1				
4.13	Stepper motor interface	50/60 mins	T1, T2, R1				
4.14	Keyboard, LCD interfacing	50/60 mins	T1, T2, R1				
4.15	Traffic light control	50/60 mins	T1, T2, R1				
UNIT-5							
5.0	ARM Architectures and Processors: ARM Architecture	50/60 mins	T2, R2				
5.1	ARM Processors Families	50/60 mins	T2, R2				
5.2	ARM Processors Families	50/60 mins	T2, R2				
5.3	ARM Cortex-M Series Family	50/60 mins	T2, R2				
5.4	ARM Cortex-M Series Family	50/60 mins	T2, R2				
5.5	ARM Cortex-M3 Processor Functional Description	50/60 mins	T2, R2				
5.6	ARM Cortex-M3 Processor Functional Description	50/60 mins	T2, R2				
5.7	Functions	50/60 mins	T2, R2				
5.8	Interfaces	50/60 mins	T2, R2				
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Evaluation Scheme:

The lectures may be slightly diverge from aforesaid plan based on students background & interest in the topic, which may perhaps include special lectures and discussions that would be planned and schedule notified accordingly.

Mid-Sem Grading:

Mid-sem marks shall be displayed after two evaluation components. (Refer Academic calendar for schedule).

Note: A student will likely be detained, if he / she doesn't appear / appear for the sake of appearing for the evaluation components / scoring zero in internal marks.

EC No	Evaluation Components	Duration	Mark	Weighta	Date & Time	Venue
NO	Components	Min	s	ge		9 6
			n (38	<u> </u>		<u>.</u>
_	MID - I		10	80%		
1	MID – II	90	10	from best		TO BE ANNOUNCED
2	QUIZ - I	20	10	Mid 20%		Z
2	QUIZ - 11	20	10	from		N
_	ASSIGNMENT - I		5	other Mid		\ \times \
3	ASSIGNMENT - II		5			0 131
4	SEM EXAMS	3 hrs.		75%		1

Attendance policies:

Attendance: Every student is expected to be responsible for regularity of the his/her attendance in class rooms and laboratories, to appear in scheduled tests and examinations and fulfill all other tasks assigned to him/her. Student should have a minimum of 75% of attendance in course to be eligible to appear for the University Examinations. As per the Govt. norms for reimbursement it is mandatory to have 75% biometric aadhar linked attendance to be eligible to scholarship.

<u>Chamber consultation hours</u>: - during free period the student can contact in my chamber for consultation regarding course.

General instructions:

Students should come prepared for classes and carry the prescribed text book(s) or material(s) as advised by the Course Faculty to the class.

Notices:

All notices concerning the course will be displayed on the respective Notice Boards

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Contact details

Prof. T. Hemalatha, Assistant Professor, Chamber No:215

email: to

tankala.hema455@gmail.com

J. Have Lettre Instructor-in-Charge

Lingayas institute of Management.
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Madalavarigudem, Vijayawada.

INSTRUCTION DIVISION HI-YEAR II-SEMESTER 2020–2021

(BIOMETRIC SYSTEM OF ATTENDENCE IS MANDATORY AS PER NORMS OF GOVT. OF AP AND JNTUK)

Course Handout

In addition to Part I (General Handout for all courses appended to the Time Table) this portion further specific details regarding the course.

L T P C

Course Code : R1632043

Course Title : VLSI DESIGN

Instructor-in-charge : Prof. J. Sambasivarao Rao

Course Objectives:

The student will be made

- Basic characteristics of MOS transistor and examines various possibilities for configuring inverter circuits and aspects of latch-up are considered.
- 2. Design processes are aided by simple concepts such as stick and symbolic diagrams but the key element is a set of design rules, which are explained clearly.
- 3. Basic circuit concepts are introduced for MOS processes we can set out approximate circuit parameters which greatly ease the design process.

Outcomes:

At the end of this course the student can able to:

- Understand the properties of MOS active devices and simple circuits configured when using them and the reason for such encumbrances as ratio rules by which circuits can be interconnected in silicon.
- Know three sets of design rules with which n-MOS and CMOS designs may be fabricated.
- 3. Understand the scaling factors determining the characteristics and performance of MOS circuits in silicon.

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SYLLABUS

UNIT-I: Introduction and Basic Electrical Properties of MOS Circuits: Introduction to IC technology. Fabrication process: n-MOS, p-MOS and CMOS, Ids versus Vds Relationships, Aspects of MOS transistor Threshold Voltage, MOS transistor Trans, Output Conductance and Figure of Merit. n-MOS Inverter, Pull-up to Pull-down Ratio for n-MOS inverter driven by another n-MOS inverter, and through one or more pass transistors. Alternative forms of pull-up, The CMOS Inverter, Latch-up in CMOS circuits, Bi-CMOS Inverter, Comparison between CMOS and Bi-CMOS technology.

UNIT-II: MOS and Bi-CMOS Circuit Design Processes: MOS Layers, Stick Diagrams, Design Rules and Layout, General observations on the Design rules, 2µm Double Metal, Double Poly, CMOS/Bi-CMOS rules, 1.2µm Double Metal, Double Poly CMOS rules, Layout Diagrams of NAND and NOR gates and CMOS inverter, Symbolic Diagrams Translation to Mask Form.

UNIT-III: Basic Circuit Concepts: Sheet Resistance, Sheet Resistance concept applied to MOS transistors and Inverters. Area Capacitance of Layers, Standard unit of capacitance, some area Capacitance Calculations, The Delay Unit, Inverter Delays, driving large capacitive loads. Propagation Delays, Wiring Capacitances, Choice of layers. Scaling of MOS Circuits: Scaling models and scaling factors, Scaling factors for device parameters, Limitations of scaling, Limits due to sub threshold currents. Limits on logic levels and supply voltage due to noise and current density. Switch logic, Gate logic.

UNIT-IV: Chip Input and Output circuits: ESD Protection, Input Circuits, Output Circuits and L(di/dt) Noise, On-Chip clock Generation and Distribution. Design for Testability: Fault types and Models. Controllability and Observability, Ad Hoc Testable Design Techniques, Scan Based Techniques and Built-In Self-Test techniques.

UNIT-V: FPGA Design: FPGA design flow, Basic FPGA architecture, FPGA Technologies, FPGA families- Altera Flex 8000FPGA, Altera Flex 10FPGA, Xilinx XC4000 series FPGA, Xilinx Spartan XL FPGA, Xilinx Spartan II FPGAs, Xilinx Vertex FPGA. Case studies: FPGA Implementation of Half adder and full adder.

Introduction to synthesis: Logic synthesis, RTL synthesis, High level Synthesis.

UNIT-VI: Introduction to Low Power VLSI Design: Introduction to Deep submicron digital IC design, Low Power CMOS Logic Circuits: Over view of power consumption, Low -power design through voltage scaling. Estimation and optimization of switching activity, Reduction of switching capacitance. Interconnect Design, Power Grid and Clock Design.

Study Material:

Text Books:

- Essentials of VLSI Circuits and Systems Kamran Eshraghian, Douglas and A. Pucknell and Sholeh Eshraghian, Prentice-Hall of India Private Limited, 2005 Edition.
- CMOS Digital Integrated Circuits Analysis and Design- Sung-Mo Kang, Yusuf Leblebici, Tata McGrawHill Education, 2003.

References: 1. Advanced Digital Design with the Verilog HDL, Michael D.Ciletti, Xilinx Design Series, Pearson Education 2. Analysis and Design of Digital Integrated Circuits in Deep submicron Technology, 3'rd edition, David Hodges.

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Vive va Nagar, MADALAVARIGUBEM: \$21212
Nitzvir' Road, Vijavawada Rufal

UNIT- TOPIC	TOPIC	TEACHING AID	REFERENCE
1.0	Introduction to IC technology Fabrication process: n-MOS, p-MOS and CMOS	РРТ	TI
1.2	lds versus Vds Relationships, Aspects of MOS transistor Threshold Voltage	BLACK BOARD	rı
1.4	MOS transistor Trans, Output Conductance and Figure of Merit.	PPT	TI TI
1.6	n-MOS Inverter, Pull-up to Pull-down Ratio for n-MOS inverter, Driven by another n-MOS inverter, and through one or more pass transistors.	BLACK BOARD	
1.8	Alternative forms of pull-up, The CMOS Inverter, Latch-up in CMOS circuits, Bi-Cmos inverter, comparison between cmos and b-cmos technology	PPT	TI
2.0	MOS Layers, Stick Diagrams, Design Rules	PPT	TI
2.2	and Layout General observations on the Design rules,2μm	PPT	TI
2.4	Double Metal, Double Poly CMOS/Bi-CMOS rules, 1.2 µm Double Metal,	PPT	TI
2.6	Double Poly CMOS rules Layout Diagrams of NAND and NOR gates	PPT.	TI
2.8	CMOS inverter Symbolic Diagrams-	PPT	TI
3.0	Sheet Resistance, Sheet Resistance concept	PPT	ΓΙ
3.2	applied to MOS transistors and Inverters Area Capacitance of Layers, Standard unit of capacitance, The Delay Unit, Inverter Delays	PPT	rı 🖋
3.4	Driving large capacitive loads, Some area Capacitance Calculations, Propagation Delays,	PPT	ΓI
3.6	Wiring Capacitances, Choice of layers Scaling models and scaling factors, Scaling factors for device parameters, Limitations of	PPT	Tł
	Limits due to sub threshold currents, Limits on	РРТ	11
5.0	logic levels ESD Protection, Input Circuits, Output	PPT	1'2

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4.2	L(di/dt) Noise, On-Chip clock Generation and Distribution	PPT	Γ2
4.4	Fault types and Models	РРТ	12
4.6	Controllability and Observability, Ad Hoc Testable Design Techniques	PPT	12
4.8	Sean Based Techniques, Built-In Self -Test techniques	PPT	T2
5.0	1 PGA design flow, Basic FPGA architecture	PPT	fi
5.2	FPGA TECHNOLOGIES, FPGA families- Altera Flex 8000FPGA	РРТ	11
5.4	Altera Flex 10FPGA, Xilinx XC4000 series FPGA, Xilinx Spartan XL FPGA	РРТ	TI
5.6	Xilinx Spartan II FPGAs, Xilinx Vertex FPGA, Case studies: FPGA Implementation of Half adder and full adder	PPT	TI
5.8	Logic synthesis, RTL synthesis, High level Synthesis	PPT	TI
6.0	Introduction to Deep submicron digital IC design, Over view of power consumption	PPT	T2
6.2	Low -power design through voltage scaling Estimation and optimization of switching activity	PPT	12
6.4	Reduction of switching capacitance	PPT	1.5
6.6	Interconnect Design	PPT	1.5
6.8	Power Grid and Clock Design	PPT	1.5



LESSON PLAN

WEEK NO	FROM	то	TOPIC NAME	NO OF TIRS
			ORINETATION	2
1	1.0	1.2	UNIT-I: Introduction and Basic Electrical Properties of MOS Circuits: Introduction to IC technology, Fabrication process: nMOS, p- MOS and CMOS. Ids versus Vds Relationships, Aspects of MOS ransistor Threshold Voltage	
2	1.4	1.8	MOS transistor Trans, Output Conductance and Figure of Merit, n-MOS Inverter, Pull-up to Pull-down Ratio for n-MOS inverter, Driven by another n-MOS inverter, and through one or more pass transistors. Alternative forms of pull-up, The CMOS Inverter, Latch-up in CMOS circuits, Bi-Cmos inverter, comparison between cmos and b-cmos technology	5
3	2.0	2.2	UNIT-II: MOS and Bi-CMOS Circuit Design Processes: MOS Layers, Stick Diagrams, Design Rules and Layout General observations on the Design rules.2µm Double Metal, Double Poly	5
4	2.4	2.6	CMOS/Bi-CMOS rules, I.2µm Double Metal, Double Poly CMOS rules, Layout Diagrams of NAND and NOR gates, CMOS inverter Symbolic Diagrams- Translation to Mask Form	5
5	2.8	2.8	Limits due to sub threshold currents, Limits on logic levels	3
6	3.0	3.2	UNIT-III: Sheet Resistance, Sheet Resistance concept applied to MOS transistors and Inverters, AreaCapacitance of Layers, Standard unit of capacitance, The Delay Unit, Inverter Delays	5
7	3.4	3.6	Driving large capacitive loads, Some area Capacitance Calculations, Propagation Delays, Wiring Capacitances, Choice of layers, Scaling models and scaling factors, Scaling factors for device parameters, Limitations of scaling	4
8	3.8	3.8	Limits due to sub threshold currents, Limits on logic levels	
9			MID-I EXAMS	
10	4.0	4.2	UNIT-IV: ESD Protection, Input Circuits, Output Circuits L(di/dt) Noise, On-Chip clock Generation and Distribution	4
11	4.4	4.6	Fault types and Models, Controllability and Observability, Ad Hoc Testable Design Techniques	

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12	4.8	4.8	Sean Based Techniques, Built-In Self -Test techniques	3
13	5.0	5.2	UNIT-V: FPGA design flow, Basic FPGA architecture FPGA TECHNOLOGIES, FPGA families- Altera Flex 8000FPGA	3
14	5.4	5.8	Altera Flex 10FPGA, Xilinx XC4000 series FPGA, Xilinx Spartan XL FPGA Xilinx Spartan HFPGAs, Xilinx Vertex FPGA, Case studies: FPGA Implementation of Half adder and full adder Logic synthesis, RTL synthesis, High level Synthesis	
15	6.0	6.2	UNIT-VI: Introduction to Deep submicron digital IC design. Over view of power consumption. Low -power design through voltage scaling Estimation and optimization of switching activity	3
16	6.4	6.8	Reduction of switching capacitance, Interconnect Design, Power Grid and Clock Design	3

EVALUATION SCHEME:

EC No	Evaluation	Duration Min	Marks	Weightage	Date & Time	Venue
1	MID – I	IVIIII	15	80% from best Mid 20% from	13-05- 2021 to 23-05-2021	
	MID – II	3Hrs	15	other Mid	23-07- 2021 to 28-07-2020	
2	QUIZ – I		10		13-05-2021 to 23-05-2020	ANNOUNCED
	QUIZ – II		10		23-07-2021 to 28-07-2020	BE ANNO
3	ASSIGNMENT - I		5			2
	ASSIGNMENT -		5			
4	SEM EXAMS	3 hrs.	70%		04-08- 2021 to 18-08-2021	



*The lectures may be slightly di-verge from aforesaid plan based on students 'background & interest in the topic, which may perhaps include special lectures and discussions that would be planned and schedule notified accordingly.

Mid-Sem Grading:

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<u>Note:</u> A student will likely be detained, if he / she doesn't appear / appear for the sake of appearing for the evaluation components / scoring zero in internal marks.

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General instructions:

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Notices:

All notices concerning the course will be displayed on the respective Notice Boards

Contact details

Prof. J SAMBASIVARAO, Assistant Professor, Chamber No. 214, email: sambasiva9841/a gmail.com

Instructor-in-Charge

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